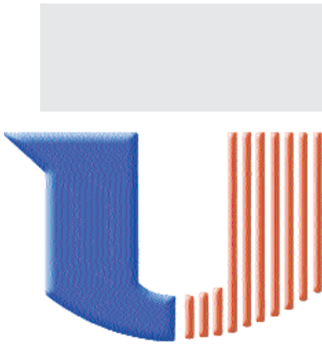

UNIVERSAL PHOTONICS
INCORPORATED

TECHNICAL DATA

UniBond Adhesives

KD SERIES

UniBond hot, water-soluble, temporary adhesives will eliminate volatile organic compounds from your process without sacrificing bond integrity. These temporary adhesives eliminate the chemicals normally used during the debonding process which harm sensitive coatings and materials. UniBond will cut cleaning time by 50% and keep you competitive by increasing yields and decreasing material costs.

Properties:

- Hot Water Soluble
- Superior Adhesion Strength
- Structural Stability
- Process Selectivity
- Convenient Application
- Bonds are rigid but not brittle

Benefits:

- Non-hazardous, biodegradable
- Safe to handle
- Sewer disposable
- Non-regulated
- Eco safe and worker safe
- Aqueous debonding takes minutes

Cost of Using Solvents:

- Hazardous and costly
- Stringent handlingprocedure
- Hazmat disposal is expensive
- Must comply with regulations
- Attendant health and safety issues
- Solvent debonding can take hours

UniBond 5.0: Lowest melting and bonding temperature. Generally used for lapping, backgrinding, wafer bonding and wafer thinning. Puddles quickly and spreads as thin as four (4) microns.

UniBond 6.5: A formulation with the properties of both UniBond 5.0 and UniBond 8.5. Great all purpose product for either lapping and grinding or slicing and dicing.

UniBond 8.5: Highest melting and bonding temperature. Used as a backfill for bonding parts that are not flat; Also for grooving, cutting, slicing and dicing hard, single crystal materials. Maintains higher tensile strength than other thermoplastics without being brittle.

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